

Low-Leakage Pico-Amp Diodes

PAD1	JPAD5	SSTPAD5
PAD5	JPAD50	SSTPAD100
PAD50		

Product Summary

Part Number	I _R Max (pA)
PAD1	-1
PAD5/JPAD5/SSTPAD5	-5
PAD50/JPAD50	-50
SSTPAD100	-100

Features

- Ultralow Leakage: PAD1 <1 pA
- Ultralow Capacitance: PAD1 <0.8 pF
- Two-Leaded Package

Benefits

- Negligible Circuit Leakage Contribution
- Circuit "Transparent" Except to Shunt High-Frequency Spikes
- Simplicity of Operation

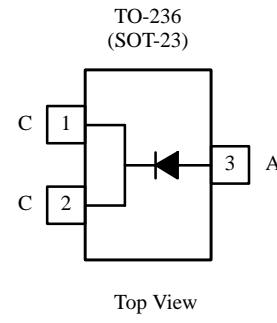
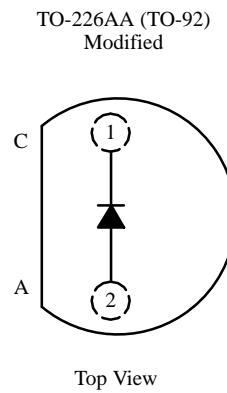
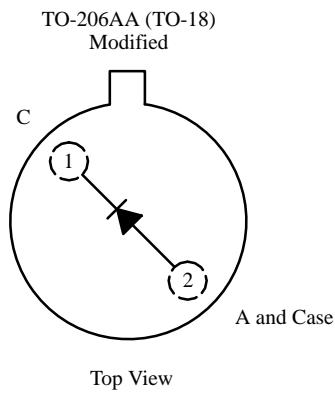
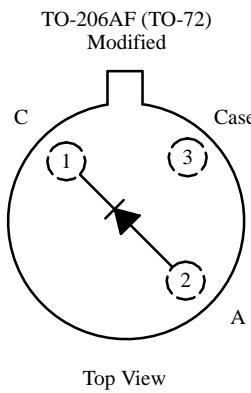
Applications

- Op Amp Input Protection
- Multiplexer Overvoltage Protection

Description

The PAD/JPAD/SSTPAD series of extremely low-leakage diodes provides a superior alternative to conventional diode technology when reverse current (leakage) must be minimized. They feature leakage currents ranging from -1 pA (PAD1) to -100 pA (SSTPAD100) to support a wide range of applications. These devices are well suited for use in applications such as input protection for operational amplifiers.

The hermetically sealed TO-206AF (TO-72) package allows full military processing per MIL-S-19500 (see Military Information). The TO-226A (TO-92) plastic package provides a low-cost option. The TO-236 (SOT-23) package provides surface-mount capability. Both J and SST series are available in tape-and-reel for automated assembly. (See Packaging Information.)



PAD1
PAD5

PAD50

JPAD5
JPAD50

SSTPAD5 (05)*
SSTPAD100 (01)

*Marking Code for TO-236

Updates to this data sheet may be obtained via facsimile by calling Siliconix FaxBack, 1-408-970-5600. Please request FaxBack document #2201.

PAD/JPAD/SSTPAD Series

TEMIC
Semiconductors

Absolute Maximum Ratings^a

Forward Current:	(PAD)	50 mA	Operation Junction Temp:	(PAD)	-55 to 175°C
	(JPAD/SSTPAD)	10 mA		(JPAD/SSTPAD) ^c	-55 to 150°C
Total Device Dissipation:	(PAD) ^b	300 mW	Lead Temperature (1/16") from case for 10 sec.)	300°C	
	(JPAD/SSTPAD) ^b	350 mW			

Notes:

- a. $T_A = 25^\circ\text{C}$ unless otherwise noted.
- b. Derate 2 mW/ $^\circ\text{C}$ above 25°C .
- c. Derate 2.8 mW/ $^\circ\text{C}$ above 25°C .

Specifications^a

Parameter	Symbol	Test Conditions	Limits			Unit
			Min	Typ ^b	Max	
Static						
Reverse Current	I_R	$V_R = -20 \text{ V}$	PAD1		-0.3	-1
			PAD5/JPAD5/SSTPAD5		-1	-5
			PAD50/JPAD50		-5	-50
			SSTPAD100		-10	-100
Reverse Breakdown Voltage	BV_R	$I_R = -1 \mu\text{A}$	PAD1/PAD5	-45	-60	
			SSTPAD5/100	-30	-55	
			All Others	-35	-55	
Forward Voltage Drop	V_F	$I_F = 1 \text{ mA}$			0.8	1.5
Dynamic						
Reverse Capacitance	C_R	$V_R = -5 \text{ V}, f = 1 \text{ MHz}$	PAD1/PAD5		0.5	0.8
			All Others		1.5	2

Notes:

- a. $T_A = 25^\circ\text{C}$ unless otherwise noted.
- b. Typical values are for DESIGN AID ONLY, not guaranteed nor subject to production testing.
- c. NT/NPA

Typical Characteristics

